

NAKAGAWA --
Application No. 10/726,660
Client/Matter: 007324-0307160

REMARKS

Claims 1 and 16 are amended. No claims are canceled or added. Accordingly, after entry of this Amendment, claims 1 and 16 will remain pending.

In the Office Action dated July 1, 2005, the Examiner rejected claim 1 under 35 U.S.C. § 103(a) as unpatentable over Fukui et al. (U.S. Patent No. 3,978,375) in view of Coucoulas (U.S. Patent No. 3,959,874) and Ebbert (U.S. Patent No. 3,898,535). In addition, the Examiner rejected claim 16 under 35 U.S.C. § 103(a) as unpatentable over Fukui et al. in view of Coucoulas. The Applicant respectfully disagrees with both rejections and, as a result, respectfully traverses the same.

In response, the Applicant respectfully submits that claim 1 is patentably distinguishable over Fukui et al., Coucoulas, and Ebbert because the claim recites a component mounting circuit board combining a number of features including, for example, a thicker metal portion provided with an exposed portion exposed outside the resin molded section on the other side of the inner electrical component. Similarly, the Applicant respectfully submits that claim 16 is patentably distinguishable over Fukui et al. and Coucoulas because the claim recites a component mounting circuit board that combines a number of features including, among them, that a thicker metal portion is embedded in the resin molded section and the resin molded section includes a portion located outside the thicker metal portion, said portion being thinner than a remaining portion of the resin molded section on the other side of the inner electrical component. Since none of the references cited by the Examiner, either alone or in combination disclose or suggest such a combination of features, the Applicant respectfully submits that claims 1 and 16 are patentable thereover.

Fukui et al. describes a wiring pattern plate 1 made of copper. (Fukui et al. at col. 2, lines 24-26.) The wiring pattern plate 1 is covered on both sides by an insulating frame 6 (see, e.g., Fig., 6), which is made of a thermosetting material. (Fukui et al. at col. 3, lines 3-7.) Fukui et al. does not describe, among other things, an inner electrical component electrically connected to one side of the circuit pattern. In addition, Fukui et al. does not describe or suggest a structure that combines a number of features including either a thicker metal portion provided with an exposed portion exposed outside the resin molded section on the other side of the inner electrical component or a thicker metal portion embedded in the resin molded section, the resin molded section including a portion located outside the thicker

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metal portion, the portion being thinner than a remaining portion of the resin molded section on the other side of the inner electrical component.

Coucoulas does not assist the Examiner with a rejection of claims 1 and 16 because Coucoulas fails to supply the deficiencies noted with respect to Fukui et al. Coucoulas describes a method of forming an integrated circuit assembly with an electrically-conductive carrier 13 (made of a ferrite material) onto which a circuit chip 11 is placed. (Coucoulas at col. 5, lines 7-11.) An insulative body 28 covers the carrier 13 and the chip 11. (Coucoulas at col. 4, lines 16-26.) Like Fukui et al., however, Coucoulas also fails to describe or suggest a structure that combines a number of features including either a thicker metal portion provided with an exposed portion exposed outside the resin molded section on the other side of the inner electrical component or a thicker metal portion embedded in the resin molded section, the resin molded section including a portion located outside the thicker metal portion, the portion being thinner than a remaining portion of the resin molded section on the other side of the inner electrical component.

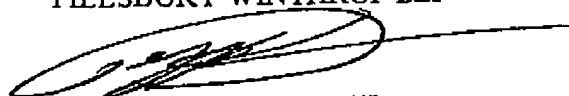
Ebbert also does not assist the Examiner in rejecting claims 1 and 16. Ebbert describes a mounting frame for electronic components with pins 13 embedded in a frame 12 made of an electrically insulative material. (Ebbert at col. 2, lines 57-67; see also Fig. 3.) While the apparatus described by Ebbert includes terminal pin portions 26 that extend laterally of the frame 12, Ebbert does not describe or suggest the combination of features recited by claims 1 and 16 that include, for example, either a thicker metal portion provided with an exposed portion exposed outside the resin molded section on the other side of the inner electrical component or a thicker metal portion embedded in the resin molded section, the resin molded section including a portion located outside the thicker metal portion, the portion being thinner than a remaining portion of the resin molded section on the other side of the inner electrical component.

Accordingly, the Applicant respectfully submits that none of the references relied upon by the Examiner may be relied upon to reject claims 1 and 16. As a result, the Applicant respectfully requests that the Examiner reconsider the rejections of the claims, withdraw the rejections, and pass this application quickly to issue.

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Respectfully submitted,
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